



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Ball et al.

**Serial No.:** 09/854,759

**Filed:** May 14, 2001

**For:** USING BACKGRIND WAFER TAPE  
TO ENABLE WAFER MOUNTING OF  
BUMPED WAFERS

**Confirmation No.:** 8899

**Examiner:** J. Haran

**Group Art Unit:** 1733

**Attorney Docket No.:** 2269-4589US  
(99-1151.00/US)

**Notice of Allowance Mailed:**

April 19, 2005

**NOTICE OF EXPRESS MAILING**

Express Mail Mailing Label Number: EL 994845459 US

Date of Deposit with USPS: July 19, 2005

Person making Deposit: Steve Wong

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Specification** begin on page 3 of this paper.

**Serial No. 09/854,759**

**Amendments to the Claims** are reflected in the listing of claims which begins on page 5 of this paper.

**Remarks** begin on page 16 of this paper.